



HFC SHIELDING

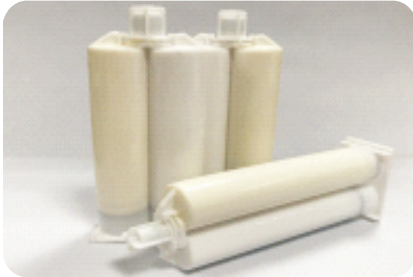
PROFESSIONAL • CONCENTRATIVE • DEDICATED

Innovative Materials Manufacturer

Two component thermal conductive gel series

【Thermal Gap filler】

DATA SHEET



- Product picture -

FEATURES:

- 1.2W/m.K thermal conductivity
- Replacing traditional assembled sheet with phase-change material
- Dispensing can be done through various manual or automatic processes
- It is Soft, can eliminates assembly stress and damping
- After curing, the required thickness can be maintained

APPLICATIONS:

- Semiconductors and radiator
- LED lamps luminaries, automotive and consumer electronics
- Being dispensed or directly coated by all kinds of thickness and shape
- High performance CPU and display card processor

APPLICATION METHODS:

- Two component thermal conductive gel can be used in various ways, including automatic dispensing and manual coating.

The series of products are accord with standards of RoHS、HSF and HALOGEN.

STORAGE CONDITIONS:Storage in the darkness

STORAGE TEMPERATURE: $\leq 30^{\circ}\text{C}$

STORAGE HUMIDITY: $\leq 70\%$

SHELF LIFE: Six months storage conditions;
Unqualified for storage conditions: 3 months.

PACKING:

- According to different needs, it can be classified into to 400cc/20L and other capacity by the way of 1:1 perfusion packaging.

BEFORE VULCANIZATION

| Items | | Parameter HTG-150DK | Unit | Test Method |
|------------------|--------------------|------------------------|-------|-----------------|
| Color | A component | gray | - | Visual |
| | B component | blue | - | Visual |
| | After mixing | Gray white | - | Visual |
| State | | Low viscosity fluid | - | - |
| Density | | 1.8(± 0.2) | g/cc | ASTM D 792 |
| Mixing ratio | | 1:1 | - | mass ratio |
| Extrusion rate | | 25(@0.6Mpa) | g/min | GB/T 29755-2013 |
| Curing condition | Surface curing | 0.5(@25°C) | H | - |
| | Complete curing | 24(@25°C) | H | - |
| | Accelerated curing | 1(@100°C) | min | - |

AFTER VULCANIZATION

| Items | Parameter | Unit | Test Method |
|-----------------------|-------------------------|---------------------------------|-------------|
| Thermal conductivity | 1.2(± 0.1) | W/m.K | ASTM D 5470 |
| Thermal resistance | ≤ 1.5 (@20psi&1mm) | $^{\circ}\text{Cin}^2/\text{W}$ | ASTM D 5470 |
| Hardness | 40(± 5) | Shore C | ASTM D 2240 |
| Breakdown voltage | ≥ 10 | KV/mm | ASTM D 149 |
| Volume resistivity | $\geq 10^{10}$ | $\Omega\cdot\text{cm}$ | ASTM D 254 |
| Compression ratio | ≥ 20 (@50Psi) | @ | ASTM D 695 |
| Tensile strength | ≥ 0.2 | Mpa | ASTM D 412 |
| Elongation | ≥ 200 | % | ASTM D 412 |
| Tear strength | ≥ 2.0 | KN/m | ASTM D 624 |
| Permittivity | ≥ 2 | @1MHz | ASTM D 150 |
| Dielectric loss | ≤ 0.1 | @1MHz | ASTM D 150 |
| UL Certification | V-0 | - | UL94 |
| Operating Temperature | -40~180 | $^{\circ}\text{C}$ | -- |

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